ON Semiconductor 10/15/2019				
Base Part		FDMF301155	HF	
Orderable Part		FDMF301155	Total weight (mg)	73.674269
Homogenous Material	Weight (mg)	Substance in Mat.	CAS#	% Avg. Weight
Clip		Zinc (Zn)	7440-66-6	0.12000727
		Iron (Fe)	7439-89-6	2.40024001
		Copper (Cu)	7440-50-8	97.3997426
	6.342949	Phosphorus (P)	7723-14-0	0.080010
Die	0.317142	Silicon (Si)	7440-21-3	100
Die Attach Solder		Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
	2.177621	Tin (Sn)	7440-31-5	5
Ероху		Titanium Dioxide (TiO2)	13463-67-7	7.99380325
		Bismaleimide	13676-54-5	26.97908598
		Ceramic	12013-47-7, 12047-27-7	8.99302866
		Aluminum Hydroxide (Al(OH)3)	21645-51-2	0.99922541
	0.1291	PTFE	9002-84-0	55.0348567
Lead Frame		Silver (Ag)	7440-22-4	5.00049771
		Zinc (Zn)	7440-66-6	0.1200104
		Iron (Fe)	7439-89-6	2.40024019
		Copper (Cu)	7440-50-8	92.39924477
	31.072307	Phosphorus (P)	7723-14-0	0.08000693
Mold Compound- Black		Ortho Cresol Novolac Resin	29690-82-2	6.49999992
		Carbon Black (C)	1333-86-4	0.50000024
		Silica (SiO2)	14464-46-1	87.99999744
	31.274585	Phenolic Resin (Novolac)	9003-35-4	5.0000024
Plating	2.100848	Tin (Sn)	7440-31-5	100
Wire Bond - Cu		Palladium (Pd)	7440-05-3	1.8
		Gold (Au)	7440-57-5	0.1
	0.259717	Copper (Cu)	7440-50-8	98.1

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF